Plano, Texas – January 16, 2020 Diodes Incorporated (Nasdaq: DIOD) today announced that its family of quad- and dual-channel 4:1 and 2:1 bus switches are now available in an ultra-thin QFN (UQFN) package. The UQFN package makes it easier for OEMs to increase PCB density and reduce product dimensions when developing PC notebooks and tablets as well as networking and telecommunications equipment.

Discrete logic devices, such as bus multiplexers and demultiplexers, remain a critical element of embedded design. The UQFN package measures just 3mm × 3mm × 0.65mm high, which is significantly smaller than comparable devices in standard packages. This smaller size allows the bus switches to be added to almost any design, even those with a high level of component density.

Each channel in the bus switches can multiplex/demultiplex a single output from between two or four inputs. While the path for all channels is selected through common inputs, the channels benefit from a dedicated active-low enable control, allowing each channel to be operated independently. All devices offer tri-state operation, presenting high-impedance outputs when the enable pin is held high.

The UQFN package used by the devices includes a thermal pad for more efficient heat dissipation. In addition, all of the devices in the four variants feature a very low on-resistance of just 5Ω, a near-zero propagation delay, and ultra-low quiescent current.

The PI3B3253ZHD and PI3B3257ZHD (dual, 4:1) and the PI3CH480ZHD and PI5C3257ZHD (quad, 2:1) bus switches have previously only been available in the QSOP and TSSOP packages, offering pin-compatibility with industry standard 74 series logic devices. The ZHD suffix on the part number denotes the UQFN package. By adding UQFN, which is one of the smallest packages available, to the packaging options, Diodes gives OEMs increased choice and even greater design flexibility.

Further information is available at www.diodes.com.
About Diodes Incorporated
Diodes Incorporated (Nasdaq: DIOD), a Standard and Poor’s SmallCap 600 and Russell 3000 Index company, is a leading global manufacturer and supplier of high-quality application specific standard products within the broad discrete, logic, analog and mixed-signal semiconductor markets. Diodes serves the consumer electronics, computing, communications, industrial, and automotive markets. Diodes’ products include diodes, rectifiers, transistors, MOSFETs, protection devices, function-specific arrays, single gate logic, amplifiers and comparators, Hall-effect and temperature sensors, power management devices, including LED drivers, AC-DC converters and controllers, DC-DC switching and linear voltage regulators, and voltage references along with special function devices, such as USB power switches, load switches, voltage supervisors, and motor controllers. Diodes also has timing, connectivity, switching, and signal integrity solutions for high-speed signals. Diodes’ corporate headquarters and Americas’ sales office are located in Plano, Texas and Milpitas, California. Design, marketing, and engineering centers are located in Plano; Milpitas; Taipei, Taiwan; Taoyuan City, Taiwan; Zhubei City, Taiwan; Manchester, England; and Neuhaus, Germany. Diodes’ wafer fabrication facilities are located in Manchester and Greenock, UK, and Shanghai, China. Diodes has assembly and test facilities located in Shanghai, Jinan, Chengdu, and Yangzhou, China, as well as in Hong Kong, Neuhaus and Taipei. Additional engineering, sales, warehouse, and logistics offices are located in Taipei; Hong Kong; Manchester; Shanghai; Shenzhen, China; Seongnam-si, South Korea; and Munich, Germany, with support offices throughout the world.

Recent news releases, annual reports and SEC filings are available at the Company’s website: http://www.diodes.com. Written requests may be sent directly to the Company, or they may be e-mailed to: diodes-fin@diodes.com.

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